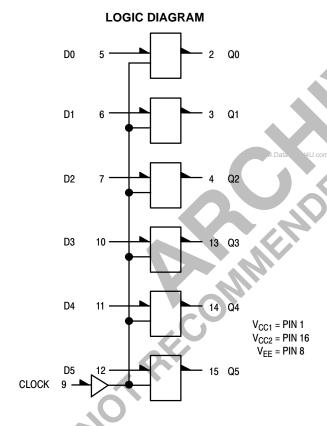
# Hex D Master/Slave Flip-Flop

The MC10176 contains six high-speed, master slave type "D" flip-flops. Clocking is common to all six flip-flops. Data is entered into the master when the clock is low. Master to slave data transfer takes place on the positive-going Clock transition. Thus, outputs may change only on a positive-going Clock transition. A change in the information present at the data (D) input will not affect the output information any other time due to the master-slave construction of this device.

- $P_D = 460 \text{ mW typ/pkg (No Load)}$
- $f_{toggle} = 150 \text{ MHz (typ)}$
- $t_r$ ,  $t_f = 2.0$  ns typ (20%–80%)



#### **CLOCKED TRUTH TABLE**

С	D	Q <sub>n+1</sub>
L	Х	Q <sub>n</sub>
H*	L	L
H*	Н	Н

\*A clock H is a clock transition from a low to a high state.

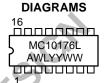


### ON Semiconductor

http://onsemi.com



CDIP-16 L SUFFIX CASE 620



**MARKING** 



PDIP-16 P SUFFIX CASE 648 16 MC10176P O AWLYYWW



PLCC-20 FN SUFFIX CASE 775



A = Assembly Location

WL = Wafer Lot

YY = Year

WW = Work Week

#### **DIP PIN ASSIGNMENT**

V <sub>CC1</sub>	1	16	$V_{CC2}$
Q0	2	15	Q5
Q1	3	14	Q4
Q2	4	13	Q3
D0	5	12	D5
D1	6	11	D4
D2	7	10	D3
$\rm V_{\rm EE}$	8	9	CLOCK

Pin assignment is for Dual-in-Line Package.
For PLCC pin assignment, see the Pin Conversion Tables on page 18 of the ON Semiconductor MECL Data Book (DL122/D).

#### **ORDERING INFORMATION**

_		_
Device	Package	Shipping
MC10176L	CDIP-16	25 Units / Rail
MC10176P	PDIP-16	25 Units / Rail
MC10176FN	PLCC-20	46 Units / Rail

#### **ELECTRICAL CHARACTERISTICS**

			Pin	Test Limits							
			Under	Under			+25°C	<del>                                     </del>	+	+85°C	Unit
	cteristic	Symbol	Test	Min	Max	Min	Тур	Max	Min	Max	
	Drain Current	Ι <sub>Ε</sub>	8		121		88	110		121	m
Input Current		I <sub>inH</sub>	5 9		350 495			220 310		220 310	μ
		l <sub>inL</sub>	5 9	0.5 0.5		0.5 0.5			0.3 0.3		μ
Output Voltag	e Logic 1	V <sub>OH</sub>	2† 15†	-1.060 -1.060	-0.890 -0.890	-0.960 -0.960		-0.810 -0.810	-0.890 -0.890	-0.700 -0.700	٧
Output Voltag	e Logic 0	V <sub>OL</sub>	2† 15†	-1.890 -1.890	-1.675 -1.675	-1.850 -1.850		-1.650 -1.650	-1.825 -1.825	-1.615 -1.615	
Threshold Vo	ltage Logic 1	V <sub>OHA</sub>	2† 15†	-1.080 -1.080		-0.980 -0.980			-0.910 -0.910		V
Threshold Vo	ltage Logic 0	V <sub>OLA</sub>	2† 15†		-1.655 -1.655			-1.630 -1.630		-1.595 -1.595	٧
Switching Tin Clock Input	nes (50Ω Load)										ı
Pro	ppagation Delay	t <sub>9+2+</sub> t <sub>9+2-</sub>	2 2	1.6 1.6	4.6 4.6	1.6 1.6		4.5 4.5	1.6 1.6	5.0 5.0	
		l .	2	1.0	4.1	1.1		4.0	1.1	4.4	
Rise Time	(20 to 80%)	t <sub>2+</sub>				11		4.0	1.1	4.4	
Rise Time Fall Time	(20 to 80%) (20 to 80%)	t <sub>2+</sub> t <sub>2-</sub>	2	1.0	4.1	1.1		4.0	1		
		t <sub>2-</sub>		1.0 2.5	4.1	2.5	8	4.0	2.5		
Fall Time			2		4.1		O	4.0			
Fall Time Setup Time Hold Time Toggle Frequ	(20 to 80%)	t <sub>2-</sub> t <sub>setup</sub> t <sub>hold</sub>	2 2 2 2	2.5 1.5 125		2.5 1.5 125	150	—— V <sub>IH</sub>	2.5 1.5 125		ı N

Output level to be measured after a clock pulse has been ap	applied to the C Input (Pin 9)	IHmax
	V	Lmin

#### **ELECTRICAL CHARACTERISTICS** (continued)

				TEST VO	LTAGE VALU	JES (Volts)		
	@ Test Te	mperature	V <sub>IHmax</sub>	V <sub>ILmin</sub>	V <sub>IHAmin</sub>	V <sub>ILAmax</sub>	V <sub>EE</sub>	
		-30°C	-0.890	-1.890	-1.205	-1.500	-5.2	
		+25°C	-0.810	-1.850	-1.105	-1.475	-5.2	
		+85°C	-0.700	-1.825	-1.035	-1.440	-5.2	
		Pin	TEST V	OLTAGE AP	PLIED TO P	NS LISTED	BELOW	
Characteristic	Symbol	Under Test	V <sub>IHmax</sub>	V <sub>ILmin</sub>	V <sub>IHAmin</sub>	V <sub>ILAmax</sub>	V <sub>EE</sub>	(V <sub>CC</sub> ) Gnd
Power Supply Drain Current	Ι <sub>Ε</sub>	8					8	1, 16
Input Current	$I_{inH}$	5 9	5 9				8 8	1, 16 1, 16
	I <sub>inL</sub>	5 9		5 9			8 8	1, 16 1, 16
Output Voltage Logic	:1 V <sub>OH</sub>	2† 15†	5 12				8 8	1, 16 1, 16
Output Voltage Logic	0 V <sub>OL</sub>	2† 15†		5 12			8 8	1, 16 1, 16
Threshold Voltage Logic	:1 V <sub>OHA</sub>	2† 15†			5 12	10.	8 8	1, 16 1, 16
Threshold Voltage Logic	0 V <sub>OLA</sub>	2† 15†				5 12	8 8	1, 16 1, 16
Switching Times (50Ω Loa	d)		+1.11Vdc	+0.31V	Pulse In	Pulse Out	−3.2 V	+2.0 V
Clock Input Propagation De	ay t <sub>9+2+</sub> t <sub>9+2-</sub>	2 2			5, 9 5, 9	2 2	8 8	1, 16 1, 16
Rise Time (20 to 80	%) t <sub>2+</sub>	2		Y	5, 9	2	8	1, 16
Fall Time (20 to 80	%) t <sub>2-</sub>	2			5, 9	2	8	1, 16
Setup Time	t <sub>setup</sub>	2			5, 9	2	8	1, 16
Hold Time	t <sub>hold</sub>	2			5, 9	2	8	1, 16
Toggle Frequency (Max)	f <sub>tog</sub>	2					8	1, 16

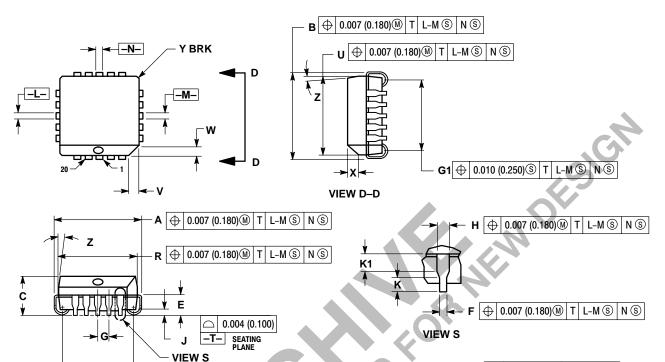
<sup>†</sup> Output level to be measured after a clock pulse has been applied to the C Input (Pin 9) VILmin VILmin

Each MECL 10,000 series circuit has been designed to meet the dc specifications shown in the test table, after thermal equilibitum has been established. The circuit is in a test socket or mounted on a printed circuit board and transverse air flow greater than 500 linear fpm is maintained. Outputs are terminated through a 50–ohm resistor to –2.0 volts. Test procedures are shown for only one gate. The other gates are tested in the same manner.

#### PACKAGE DIMENSIONS

#### PLCC-20 **FN SUFFIX**

PLASTIC PLCC PACKAGE CASE 775-02 ISSUE C



#### NOTES:

G1 ⊕ 0.010 (0.250)③ T L-M ⑤ N ⑤

OF MICE. NOT PERSON

- OTES:

  1. DATUMS -L-, -M-, AND -N- DETERMINED WHERE TOP OF LEAD SHOULDER EXITS PLASTIC BODY AT MOLD PARTING LINE.

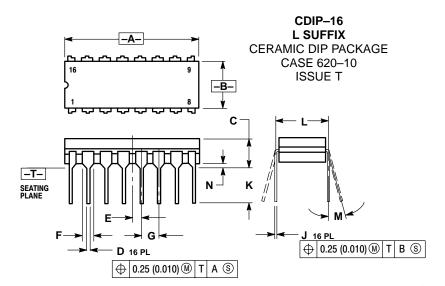
  2. DIMENSION G1, TRUE POSITION TO BE MEASURED AT DATUM -T-, SEATING PLANE.

  3. DIMENSIONS R AND U DO NOT INCLUDE MOLD FLASH. ALLOWABLE MOLD FLASH IS 0.010 (0.250) PER SIDE.

  4. DIMENSIONING AND TOLERANCING PER ANSI V14 5M 1982
- Y14.5M, 1982. CONTROLLING DIMENSION: INCH.
- THE PACKAGE TOP MAY BE SMALLER THAN THE PACKAGE BOTTOM BY UP TO 0.012 (0.300). DIMENSIONS R AND U ARE DETERMINED AT THE OUTERMOST EXTREMES OF THE PLASTIC BODY EXCLUSIVE OF MOLD FLASH, TIE BAR BURRS, GATE BURRS AND INTERLEAD FLASH, BUT
- INCLUDING ANY MISMATCH BETWEEN THE TOP AND BOTTOM OF THE PLASTIC BODY. DIMENSION H DOES NOT INCLUDE DAMBAR PROTRUSION OR INTRUSION. THE DAMBAR PROTRUSION(S) SHALL NOT CAUSE THE H DIMENSION TO BE GREATER THAN 0.037 (0.940). THE DAMBAR INTRUSION(S) SHALL NOT CAUSE THE H DIMENSION TO BE SMALLER THAN 0.025 (0.635).

	INC	HES	MILLIM	ETERS
DIM	MIN	MAX	MIN	MAX
Α	0.385	0.395	9.78	10.03
В	0.385	0.395	9.78	10.03
С	0.165	0.180	4.20	4.57
Ε	0.090	0.110	2.29	2.79
F	0.013	0.019	0.33	0.48
G	0.050	BSC	1.27	BSC
Н	0.026	0.032	0.66	0.81
J	0.020		0.51	
K	0.025		0.64	
R	0.350	0.356	8.89	9.04
U	0.350	0.356	8.89	9.04
٧	0.042	0.048	1.07	1.21
W	0.042	0.048	1.07	1.21
X	0.042	0.056	1.07	1.42
Υ		0.020		0.50
Z	2°	10°	2°	10 °
G1	0.310	0.330	7.88	8.38
K1	0.040		1.02	

#### PACKAGE DIMENSIONS



#### NOTES:

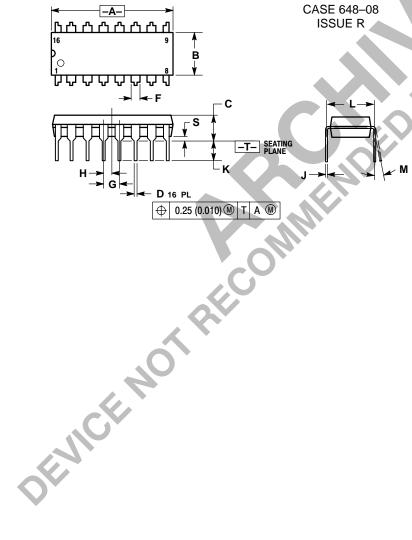
- DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
   CONTROLLING DIMENSION: INCH.
   DIMENSION LTO CENTER OF LEAD WHEN CONTROLLING DIMENSION LTO CENTER OF LEAD WHEN

- FORMED PARALLEL

  DIMENSION F MAY NARROW TO 0.76 (0.030)
  WHERE THE LEAD ENTERS THE CERAMIC
  BODY.

	INC	HES	MILLIN	IETERS	
DIM	MIN	MAX	MIN	MAX	
Α	0.750	0.785	19.05	19.93	
В	0.240	0.295	6.10	7.49	
С		0.200		5.08	
D	0.015	0.020	0.39	0.50	
E	0.050	BSC	1.27 BSC		
F	0.055	0.065	1.40	1.65	
G	0.100	BSC	2.54	BSC	
Н	0.008	0.015	0.21	0.38	
K	0.125	0.170	3.18	4.31	
L	0.300	BSC	7.62	BSC	
М	0 °	15°	0 °	15°	
N	0.020	0.040	0.51	1.01	

#### PDIP-16 **P SUFFIX** PLASTIC DIP PACKAGE CASE 648-08 ISSUE R



- NOTES:
  1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
  2. CONTROLLING DIMENSION: INCH.
  3. DIMENSION L TO CENTER OF LEADS WHEN FORMED PARALLEL.
  4. DIMENSION B DOES NOT INCLUDE MOLD FLASH.
  5. ROUNDED CORNERS OPTIONAL

	INC	HES	MILLIN	IETERS
DIM	MIN	MAX	MIN	MAX
Α	0.740	0.770	18.80	19.55
В	0.250	0.270	6.35	6.85
С	0.145	0.175	3.69	4.44
D	0.015	0.021	0.39	0.53
F	0.040	0.70	1.02	1.77
G	0.100	BSC	2.54	BSC
Н	0.050	BSC	1.27	BSC
J	0.008	0.015	0.21	0.38
K	0.110	0.130	2.80	3.30
L	0.295	0.305	7.50	7.74
M	0°	10°	0°	10 °
S	0.020	0.040	0.51	1.01

## **Notes**



## **Notes**





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